

**N - CHANNEL ENHANCEMENT MODE POWER MOSFET**

SGT MOS、低内阻、低结电容开关损耗小

**TFD150N03MG****• General Description**

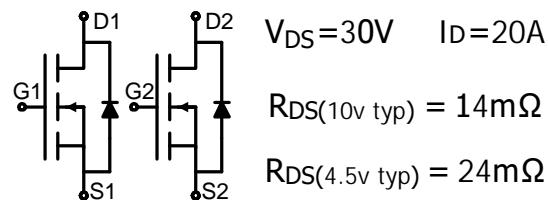
The TFD150N03MG combines advanced trench MOSFET technology with a low resistance package to provide extremely low RDS(ON). This device is ideal for load switch and battery protection applications.

**• Features**

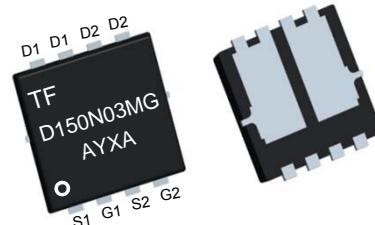
- Advance high cell density Trench technology
- Low RDS(ON) to minimize conductive loss
- Low Gate Charge for fast switching
- Dual DIE in one package

**• Application**

- Power Management in Notebook Computer,
- Portable Equipment and Battery
- Powered Systems

**• Product Summary**

$V_{DS} = 30V$     $I_D = 20A$   
 $R_{DS(10V\ typ)} = 14m\Omega$   
 $R_{DS(4.5V\ typ)} = 24m\Omega$

**PDFN3333-8****• Package Marking and Ordering Information:**

Part NO.	TFD150N03MG
Marking1	D150N03MG:TFD150N03MG
Marking2	TF:tuofeng; Y:year code; X:Week; AA:device code;
Basic ordering unit (pcs)	5000

**• Absolute Maximum Ratings ( $T_C = 25^\circ C$ )**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D @ T_C = 25^\circ C$	20	A
	$I_D @ T_C = 75^\circ C$	14	A
	$I_D @ T_C = 100^\circ C$	12	A
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	50	A
Total Power Dissipation	$P_D @ T_C = 25^\circ C$	35	W
Total Power Dissipation	$P_D @ T_A = 25^\circ C$	1.2	W
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy	$E_{AS}$	30	mJ



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•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	4.5	° C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	68	° C/W
Soldering temperature, wavesoldering for 8 s	T <sub>sold</sub>	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30	-	-	V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250μA	1.0	1.7	2.0	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =30 V <sub>GS</sub> = 0V	-	-	1.0	μA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V , V <sub>DS</sub> = 0V	-	-	±100	nA
Static Drain-source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =8A	-	14	18	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	-	24	27	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 25V, I <sub>D</sub> =8A	-	8	-	S
Source-drain voltage	V <sub>SD</sub>	I <sub>S</sub> =8A	-	-	1.20	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C <sub>iss</sub>	f = 1MHz V <sub>DS</sub> =20V V <sub>GS</sub> =0V	-	300	-	pF
Output capacitance	C <sub>oss</sub>		-	65	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	60	-	

•Gate Charge characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> = 20V I <sub>D</sub> = 8A V <sub>GS</sub> = 10V	-	11.1	-	nC
Gate - Source charge	Q <sub>gs</sub>		-	2.07	-	
Gate - Drain charge	Q <sub>gd</sub>		-	2.34	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;



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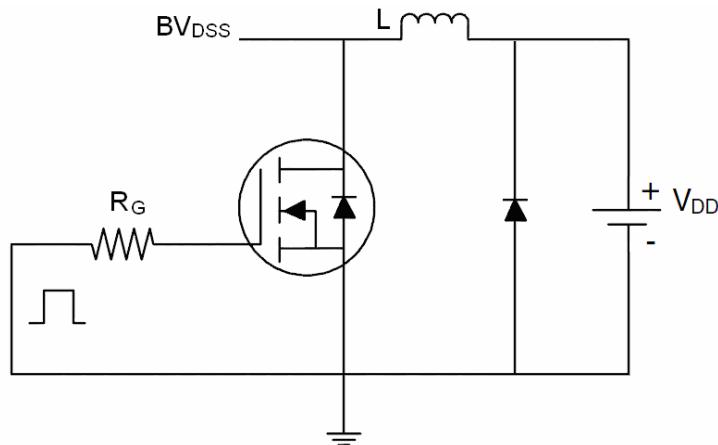
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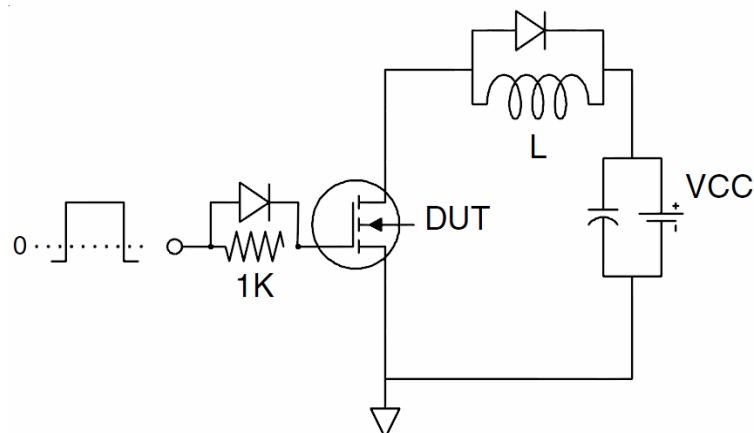
**TFD150N03MG**

### Test Circuit

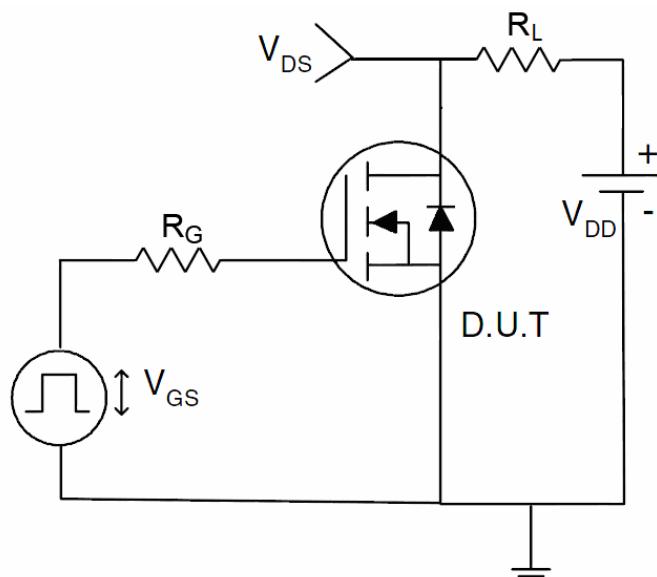
#### 1) $E_{AS}$ test Circuit



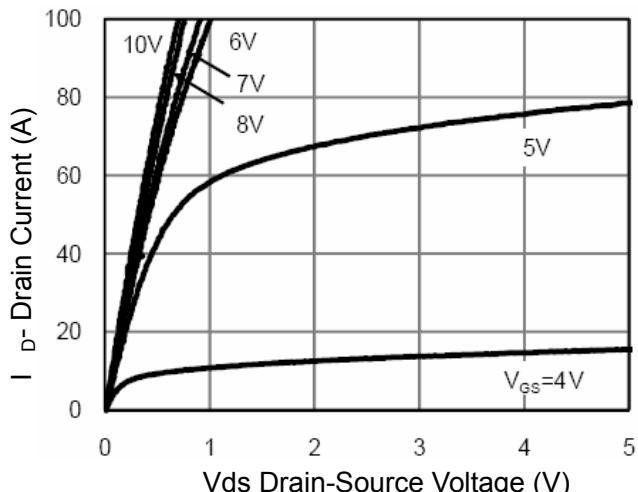
#### 2) Gate charge test Circuit



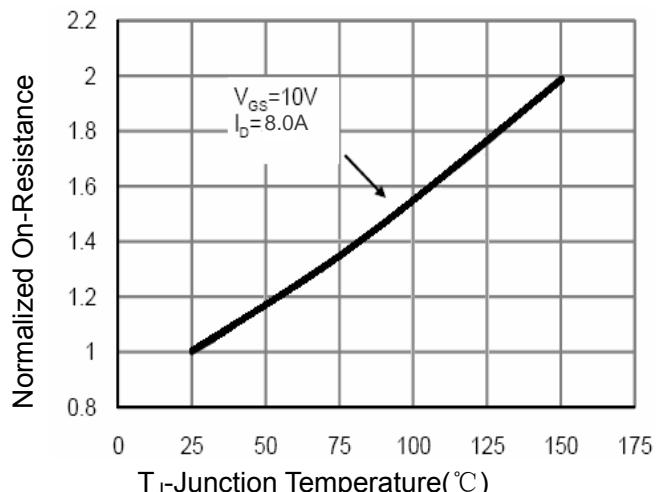
#### 3) Switch Time Test Circuit



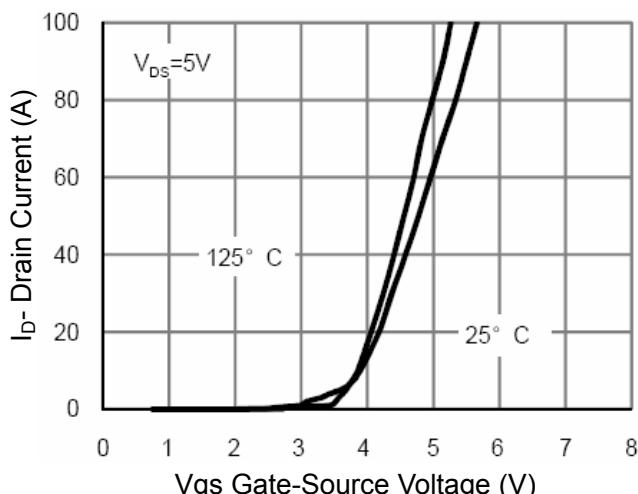
### Typical Electrical and Thermal Characteristics



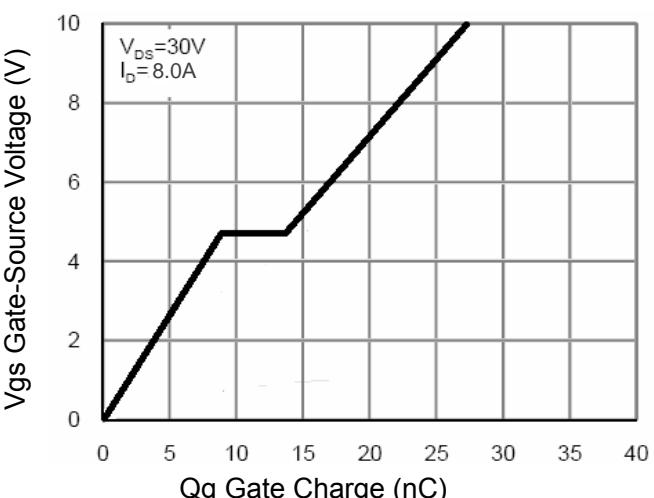
**Figure 1 Output Characteristics**



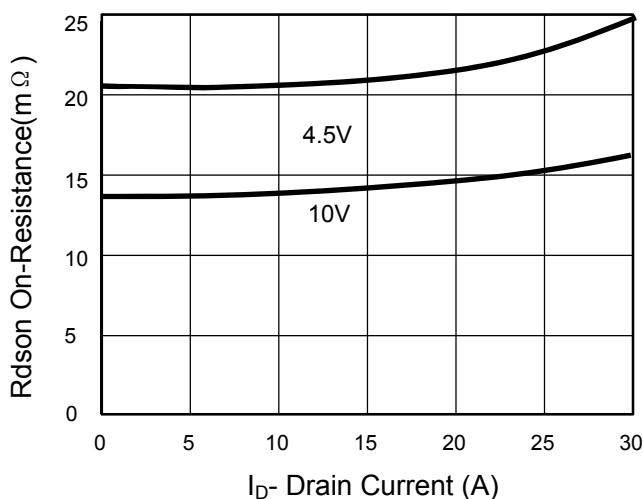
**Figure 4 Rdson-JunctionTemperature**



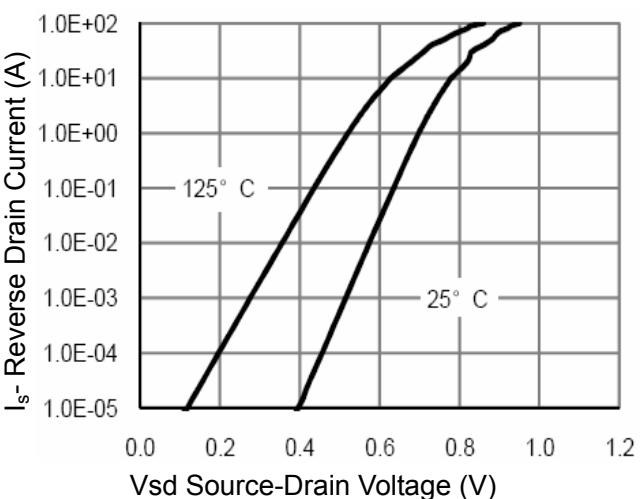
**Figure 2 Transfer Characteristics**



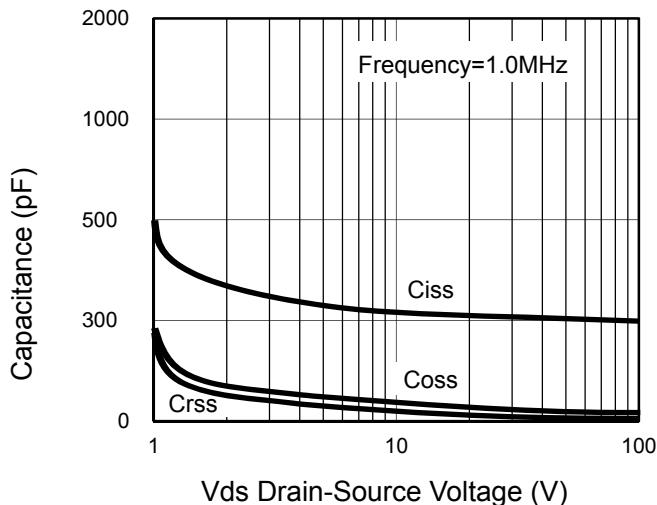
**Figure 5 Gate Charge**



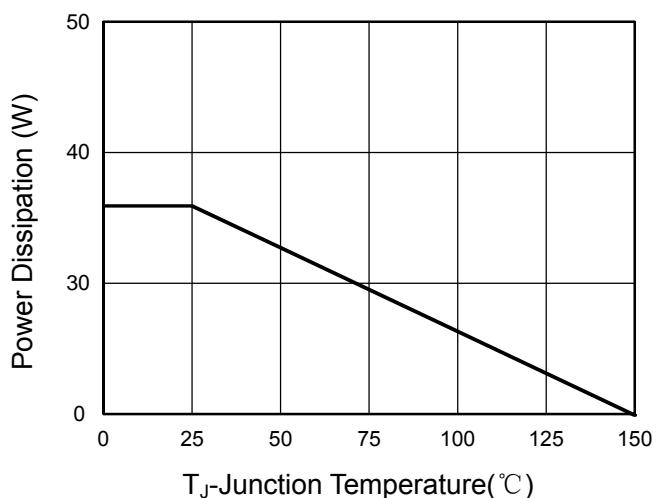
**Figure 3 Rdson- Drain Current**



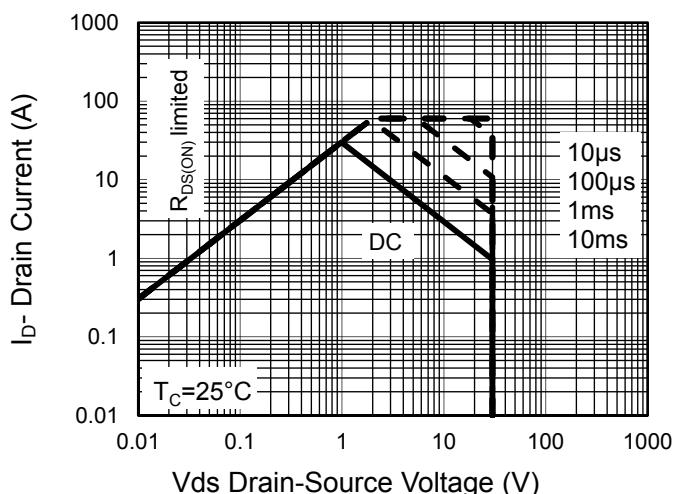
**Figure 6 Source- Drain Diode Forward**



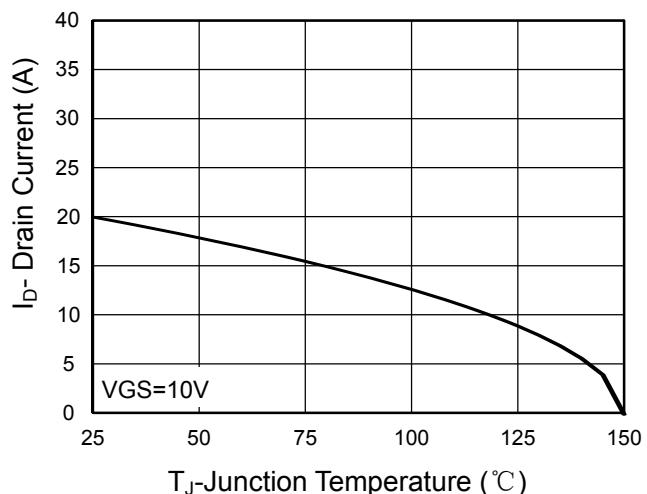
**Figure 7 Capacitance vs Vds**



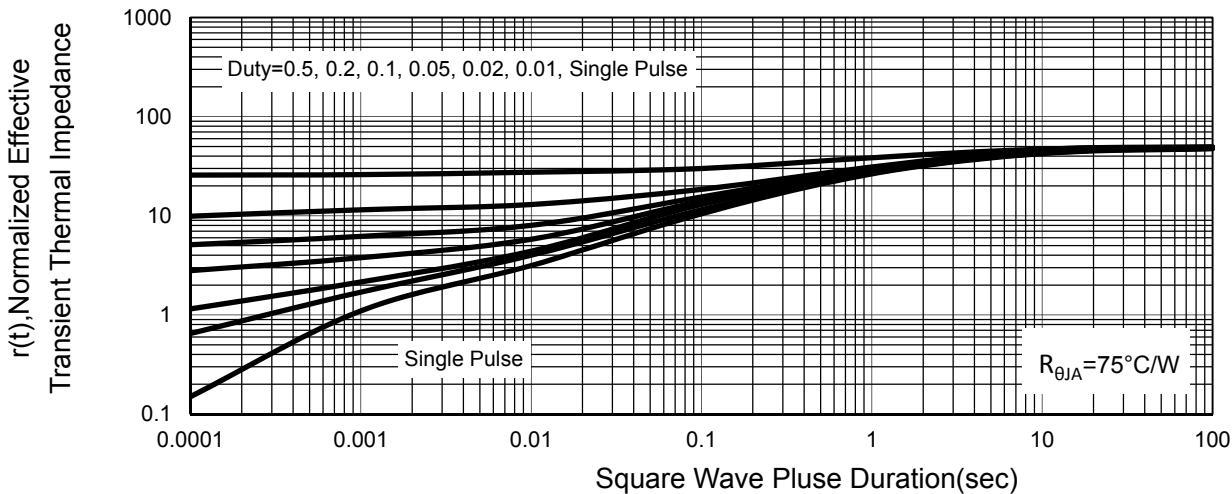
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**



**Figure 10 Current De-rating**



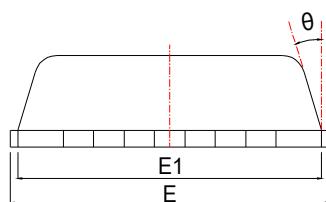
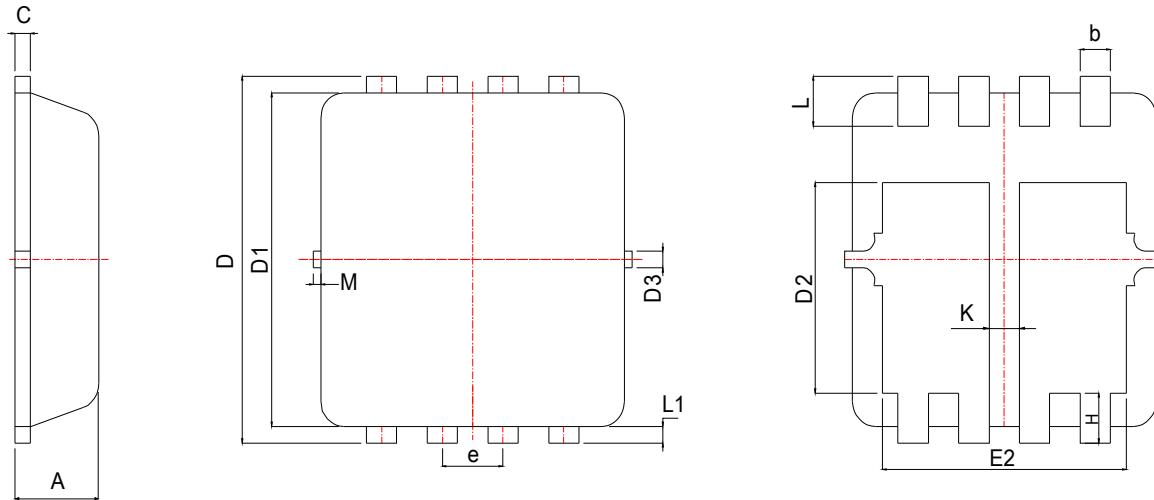
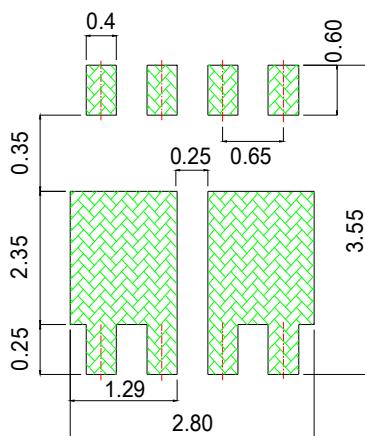
**Figure 11 Normalized Maximum Transient Thermal Impedance**



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(Only for Reference)

SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031	E1	3.00	3.15	3.20	0.118	0.122	0.126
b	0.25	0.30	0.35	0.010	0.012	0.014	E2	2.39	2.49	2.59	0.094	0.098	0.102
c	0.10	0.15	0.25	0.004	0.007	0.010	e	0.65BSC			0.026BSC		
D	3.25	3.35	3.45	0.128	0.132	0.136	H	0.30	0.40	0.50	0.012	0.016	0.020
D1	3.00	3.10	3.20	0.118	0.122	0.126	L	0.30	0.40	0.50	0.012	0.016	0.020
D2	1.78	1.88	1.98	0.070	0.074	0.078	L1	*	0.13	*	*	0.005	*
D3	*	0.13	*	*	0.005	*	M	*	*	10°	12°	10°	12°
E	3.20	3.30	3.40	0.126	0.130	0.134	θ	*	*	0.15	*	*	0.006
K	0.30	*	*	0.012	*	*							